

AN 1983:523789 CAPLUS
 DN 99:123789
 TI Flexible printed circuit boards
 PA Hitachi Chemical Co., Ltd., Japan
 SO Jpn. Kokai Tokkyo Koho, 3 pp.
 CODEN: JKXXAF
 DT Patent
 LA Japanese
 IC H05K001-03; H05K001-02
 CC 38-3 (Plastics Fabrication and Uses)
 Section cross-reference(s): 76

JP 58-42290

409
 withdrawn

FAN. CNT 1

	PATENT NO.	KIND	DATE	APPLICATION NO.	DATE
✓ PI	JP 58042290	A2	19830311	JP 1981-141489	19810907
AB	Thin, mech. strong circuit boards having excellent heat and moisture resistance comprise fluoropolymer films pretreated for good adhesion and coated on both sides with heat-resistant polymers contg. heterocyclic groups or precursors thereof, then heat treated and laminated with metal foil. Thus, a 50-.mu. PTFE [9002-84-0] film was pretreated in aq. alkali, then dipped in a 20% soln. of HI-400 [25119-99-7] (polyimide) in N-methyl-2-pyrrolidone, dried 30 min at 150.degree., and baked 30 min at 250.degree. to obtain a <u>flexible board</u> 75-.mu. thick, which was <u>laminated</u> with Cu foil using a mixt. of EP-4000 [11121-15-6] and Epikote 828 [25068-38-6] epoxy resins and B-002 [39387-07-0] (heterocyclic polyamine). The resulting board showed no sign of damage after exposure to solder at 260.degree. for 30 s.				
ST	flexible circuit board PTFE polyimide; heat moisture resistant circuit board				
IT	Epoxy resins, uses and miscellaneous RL: TEM (Technical or engineered material use); USES (Uses) (adhesives, for bonding copper foil to polyimide surfaces)				
IT	Fluoropolymers RL: USES (Uses) (films, contg. heterocyclic polymer reinforcing coatings, for flexible circuit boards)				
IT	Plastics, film RL: USES (Uses) (fluoropolymers contg. heterocyclic polymer reinforcing coatings, for flexible printed circuit boards)				
IT	Coating materials (heterocyclic polymers, for reinforcing of fluoropolymer films, for flexible printed circuit boards)				
IT	Heat-resistant materials (polyimide-coated PTFE films, for flexible printed circuit boards)				
IT	Electric circuits (printed, boards, flexible, fluoropolymer films coated with heterocyclic polymers, heat- and moisture-resistant)				
IT	11121-15-6	25068-38-6			
	RL: TEM (Technical or engineered material use); USES (Uses) (adhesives, for bonding copper foil to polyimide surfaces)				
IT	25119-99-7				
	RL: USES (Uses) (coatings, reinforcing, on fluoropolymer films, for flexible printed circuit boards)				
IT	39387-07-0				
	RL: MOA (Modifier or additive use); USES (Uses) (crosslinking agents, for epoxy adhesives bonding copper foil to polyimide surfaces)				

RN 11121-15-6 REGISTRY
 CN Poly[oxy(methyl-1,2-ethanediyl)],
 .alpha.,.alpha.'-[(1-methylethylidene)di-
 4,1-phenylene]bis[.omega.-(oxiranylmethoxy)-, homopolymer (9CI) (CA

INDEX

NAME)

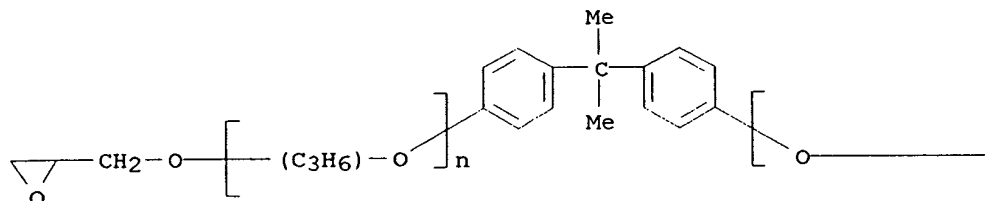
OTHER NAMES:

CN Adeka EP 4000
 CN Adeka Resin EP 4000
 CN ADK 4000
 CN EP 4000
 CN Epiclon 717
 CN Gurishieru BPP 350
 CN **Rikaresin BPO 20E**
 DR 54667-37-7, 60267-15-4, 63278-42-2, 39354-76-2
 MF ((C3 H6 O)n (C3 H6 O)n C21 H24 O4)x
 CI PMS, COM
 PCT Epoxy resin, Polyether
 LC STN Files: CA, CAPLUS, CHEMLIST, IFICDB, IFIPAT, IFIUDB, USPATFULL

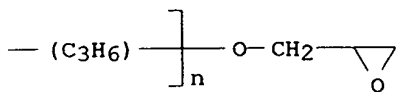
CM 1

CRN 55236-42-5
 CMF (C3 H6 O)n (C3 H6 O)n C21 H24 O4
 CCI IDS, PMS

PAGE 1-A



PAGE 1-B



93 REFERENCES IN FILE CA (1967 TO DATE)
 23 REFERENCES TO NON-SPECIFIC DERIVATIVES IN FILE CA
 93 REFERENCES IN FILE CAPLUS (1967 TO DATE)